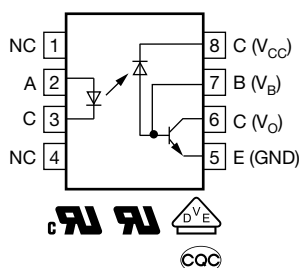
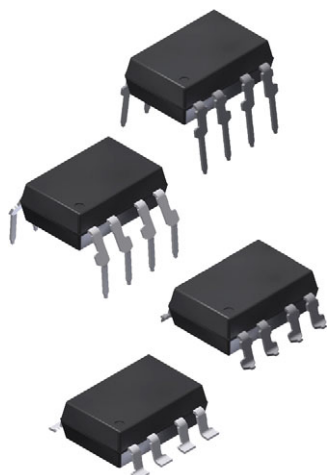


High Speed Optocoupler, 1 MBd, Photodiode With Transistor Output



DESCRIPTION

The 6N136 is an optocoupler with a GaAlAs infrared emitting diode, optically coupled with an integrated photo detector which consists of a photo diode and a high speed transistor in a DIP-8 plastic package.

Signals can be transmitted between two electrically separated circuits up to frequencies of 2 MHz. The potential difference between the circuits to be coupled should not exceed the maximum permissible reference voltages.

FEATURES

- Isolation test voltages: 5300 V_{RMS}
- TTL compatible
- High bit rates: 1 Mbit/s
- High common-mode interference immunity
- Bandwidth 2 MHz
- Open-collector output
- External base wiring possible
- Material categorization:

for definitions of compliance please see www.vishay.com/doc?99912



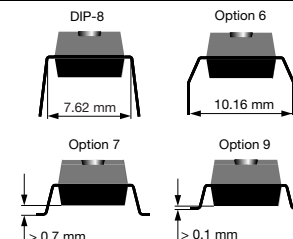
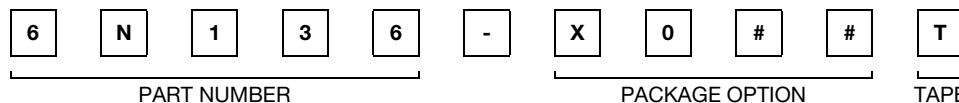
RoHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

AGENCY APPROVALS

- [UL](#)
- [cUL](#)
- [DIN EN 60747-5-5 \(VDE0884-5\) available with option 1](#)
- [CQC](#)

LINKS TO ADDITIONAL RESOURCES



ORDERING INFORMATION


AGENCY CERTIFIED / PACKAGE	CTR (%)
UL, cUL, CQC	≥ 19
DIP-8	6N136
DIP-8, 400 mil, option 6	6N136-X006
SMD-8, option 7	6N136-X007T ⁽¹⁾
SMD-8, option 9	6N136-X009T ⁽¹⁾
UL, cUL, CQC, VDE (Option 1)	≥ 19
DIP-8	6N136-X001
SMD-8, option 7	6N136-X017T
SMD-8, option 9	6N136-X019T

Note

⁽¹⁾ Also available in tubes; do not add T to end

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

PARAMETER	CONDITION	SYMBOL	VALUE	UNIT
INPUT				
Reverse voltage		V_R	5	V
Forward current		I_F	25	mA
Peak forward current	$t = 1\text{ ms}$, duty cycle 50 %	I_{FSM}	50	mA
Maximum surge forward current	$t \leq 1\text{ }\mu\text{s}$, 300 pulses/s		1	A
Thermal resistance		R_{th}	700	K/W
Power dissipation	$T_{amb} = 70\text{ }^{\circ}\text{C}$	P_{diss}	45	mW
OUTPUT				
Supply voltage		V_S	-0.5 to 15	V
Output voltage		V_O	-0.5 to 15	V
Emitter base voltage		V_{EBO}	5	V
Output current		I_O	8	mA
Maximum output current			16	mA
Base current		I_B	5	mA
Thermal resistance			300	K/W
Power dissipation	$T_{amb} = 70\text{ }^{\circ}\text{C}$	P_{diss}	100	mW
COUPLER				
Storage temperature range		T_{stg}	-55 to +150	$^{\circ}\text{C}$
Ambient temperature range		T_{amb}	-55 to +100	$^{\circ}\text{C}$
Soldering temperature	Max. $\leq 10\text{ s}$, dip soldering $\geq 0.5\text{ mm}$ from case bottom	T_{sld}	260	$^{\circ}\text{C}$

Note

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.



ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT						
Forward voltage	$I_F = 16\text{ mA}$	V_F	-	1.33	1.9	V
Breakdown voltage	$I_R = 10\text{ }\mu\text{A}$	V_{BR}	5	-	-	V
Reverse current	$V_R = 5\text{ V}$	I_R	-	0.5	10	μA
Capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$	C_O	-	30	-	pF
Temperature coefficient, forward voltage	$I_F = 16\text{ mA}$	$\Delta V_F / \Delta T_A$	-	-1.7	-	mV/ $^{\circ}\text{C}$
OUTPUT						
Logic low supply current	$I_F = 16\text{ mA}$, $V_O = \text{open}$, $V_{CC} = 15\text{ V}$	I_{CCL}	-	150	-	μA
Logic high supply current	$I_F = 0\text{ mA}$, $V_O = \text{open}$, $V_{CC} = 15\text{ V}$	I_{CCH}	-	0.01	1	μA
Output voltage, output low	$I_F = 16\text{ mA}$, $I_O = 3.0\text{ mA}$, $V_{CC} = 4.5\text{ V}$	V_{OL}	-	0.1	0.4	V
Output current, output high	$I_F = 0\text{ mA}$, $V_O = V_{CC} = 5.5\text{ V}$	I_{OH}	-	3	500	nA
	$I_F = 0\text{ mA}$, $V_O = V_{CC} = 15\text{ V}$	I_{OH}	-	0.01	1	μA
COUPLER						
Capacitance (input to output)	$f = 1\text{ MHz}$	C_{IO}	-	0.6	-	pF

Note

- Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

CURRENT TRANSFER RATIO ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Current transfer ratio	$I_F = 16\text{ mA}$, $V_O = 0.4\text{ V}$, $V_{CC} = 4.5\text{ V}$	CTR	19	35	-	%
	$I_F = 16\text{ mA}$, $V_O = 0.5\text{ V}$, $V_{CC} = 4.5\text{ V}$	CTR	15	-	-	%

SWITCHING CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
High to low	$I_F = 16\text{ mA}$, $V_{CC} = 5\text{ V}$, $R_L = 1.9\text{ k}\Omega$	t_{PHL}	-	0.2	0.8	μs
Low to high	$I_F = 16\text{ mA}$, $V_{CC} = 5\text{ V}$, $R_L = 1.9\text{ k}\Omega$	t_{PLH}	-	0.2	0.8	μs

COMMON MODE TRANSIENT IMMUNITY ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
High	$I_F = 0\text{ mA}$, $V_{CM} = 10\text{ V}_{P-P}$, $V_{CC} = 5\text{ V}$, $R_L = 1.9\text{ k}\Omega$	$ CM_H $	-	1000	-	V/ μs
Low	$I_F = 16\text{ mA}$, $V_{CM} = 10\text{ V}_{P-P}$, $V_{CC} = 5\text{ V}$, $R_L = 1.9\text{ k}\Omega$	$ CM_L $	-	1000	-	V/ μs

SAFETY AND INSULATION RATINGS				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Climatic classification	According to IEC 68 part 1		55 / 100 / 21	
Pollution degree	According to DIN VDE 0109		2	
Comparative tracking index	Insulation group IIIa	CTI	175	
Maximum rated withstanding isolation voltage	According to UL1577, t = 1 min	V_{ISO}	5300	V_{RMS}
Maximum transient isolation voltage	According to DIN EN 60747-5-5	V_{IOTM}	8000	V_{peak}
Maximum repetitive peak isolation voltage	According to DIN EN 60747-5-5	V_{IORM}	890	V_{peak}
Isolation resistance	$T_{amb} = 25\text{ }^{\circ}\text{C}$, $V_{IO} = 500\text{ V}$	R_{IO}	$\geq 10^{12}$	Ω
	$T_{amb} = 100\text{ }^{\circ}\text{C}$, $V_{IO} = 500\text{ V}$	R_{IO}	$\geq 10^{11}$	Ω
Output safety power		P_{SO}	500	mW
Input safety current		I_{SI}	300	mA
Input safety temperature		T_S	175	$^{\circ}\text{C}$
Creepage distance	DIP-8		≥ 7	mm
Clearance distance	DIP-8		≥ 7	mm
Creepage distance	DIP-8, 400 mil, option 6		≥ 8	mm
Clearance distance	DIP-8, 400 mil, option 6		≥ 8	mm
Creepage distance	SMD-8, option 7		≥ 8	mm
Clearance distance	SMD-8, option 7		≥ 8	mm
Creepage distance	SMD-8, option 9		≥ 8	mm
Clearance distance	SMD-8, option 9		≥ 8	mm
Insulation thickness		DTI	≥ 0.4	mm

Note

- As per IEC 60747-5-5, § 7.4.3.8.2, this optocoupler is suitable for “safe electrical insulation” only within the safety ratings. Compliance with the safety ratings shall be ensured by means of protective circuits.

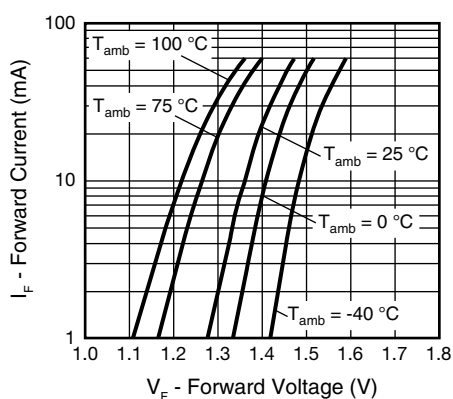
TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 1 - LED Forward Current vs. Forward Voltage

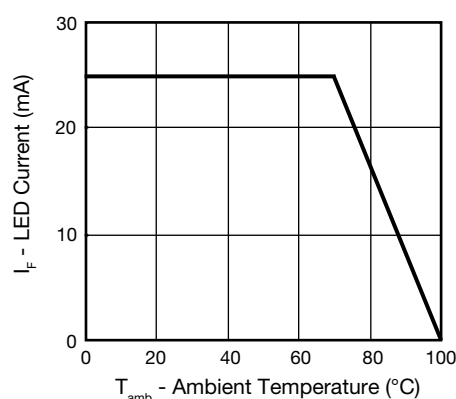


Fig. 2 - Permissible Forward LED Current vs. Temperature

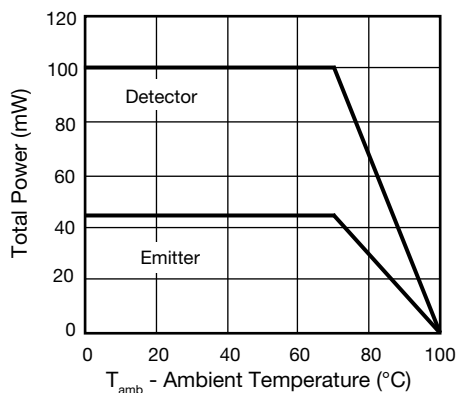


Fig. 3 - Permissible Power Dissipation vs. Temperature

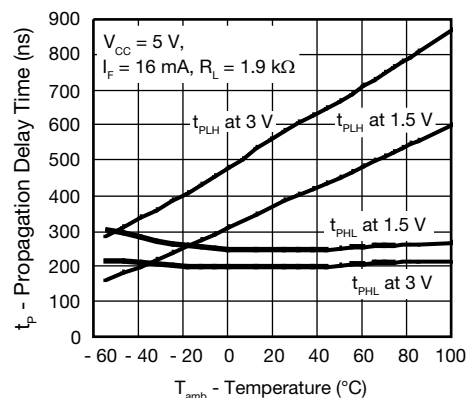


Fig. 6 - Propagation Delay vs. Ambient Temperature

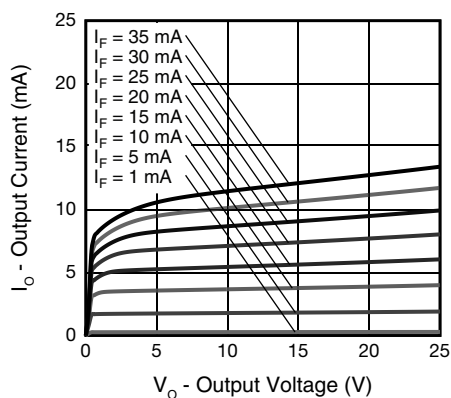


Fig. 4 - Output Current vs. Output Voltage

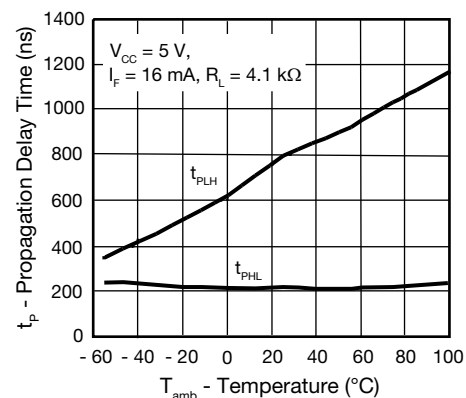


Fig. 7 - Propagation Delay vs. Ambient Temperature

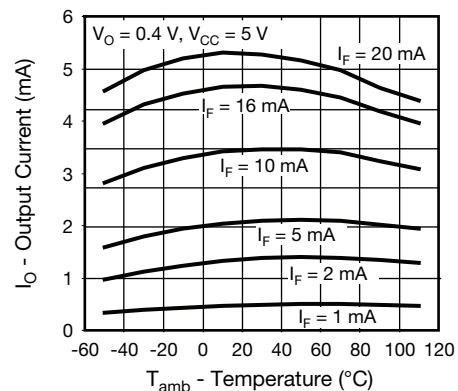


Fig. 5 - Output Current vs. Temperature

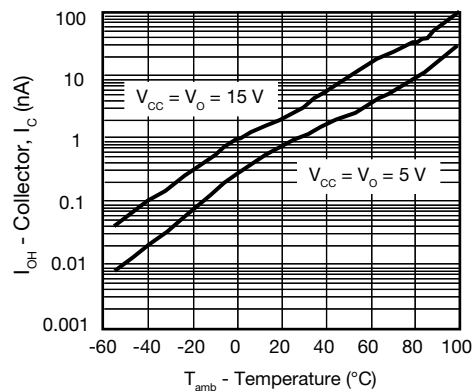


Fig. 8 - Logic High Output Current vs. Temperature

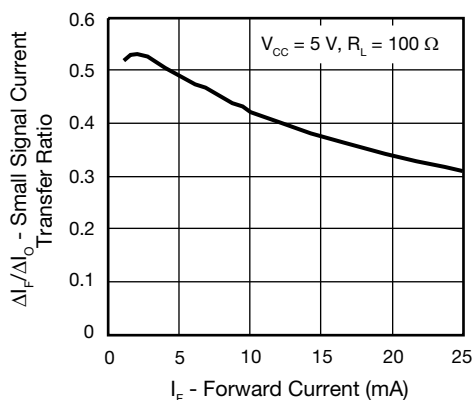


Fig. 9 - Small Signal Current Transfer Ratio vs. Quiescent Input Current

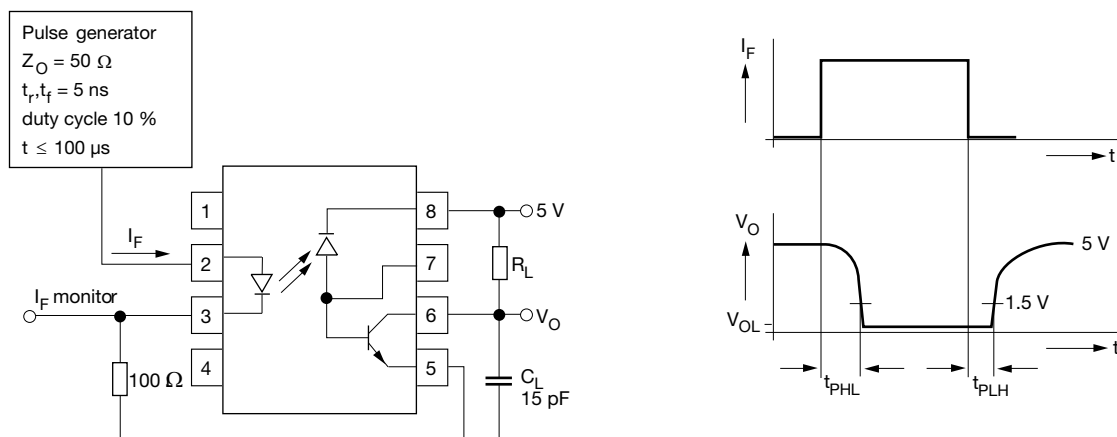


Fig. 10 - Switching Times

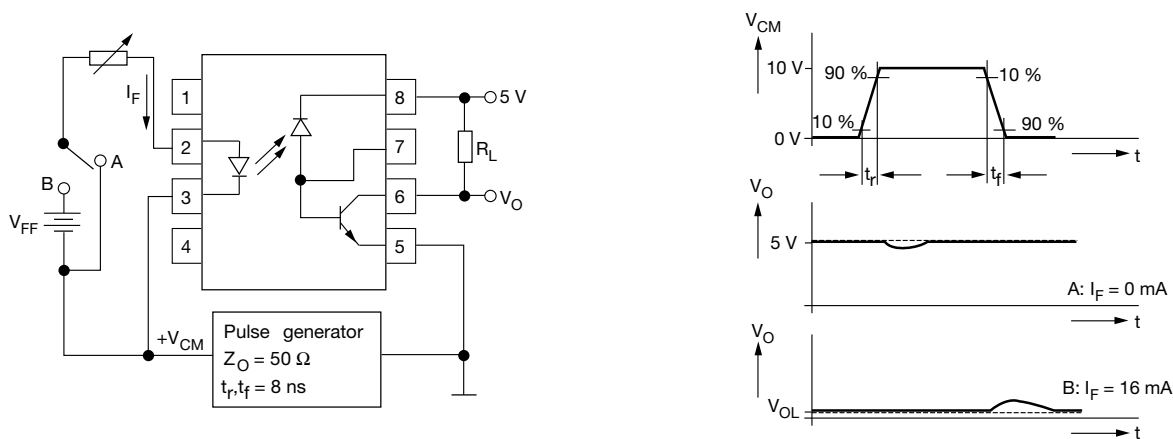
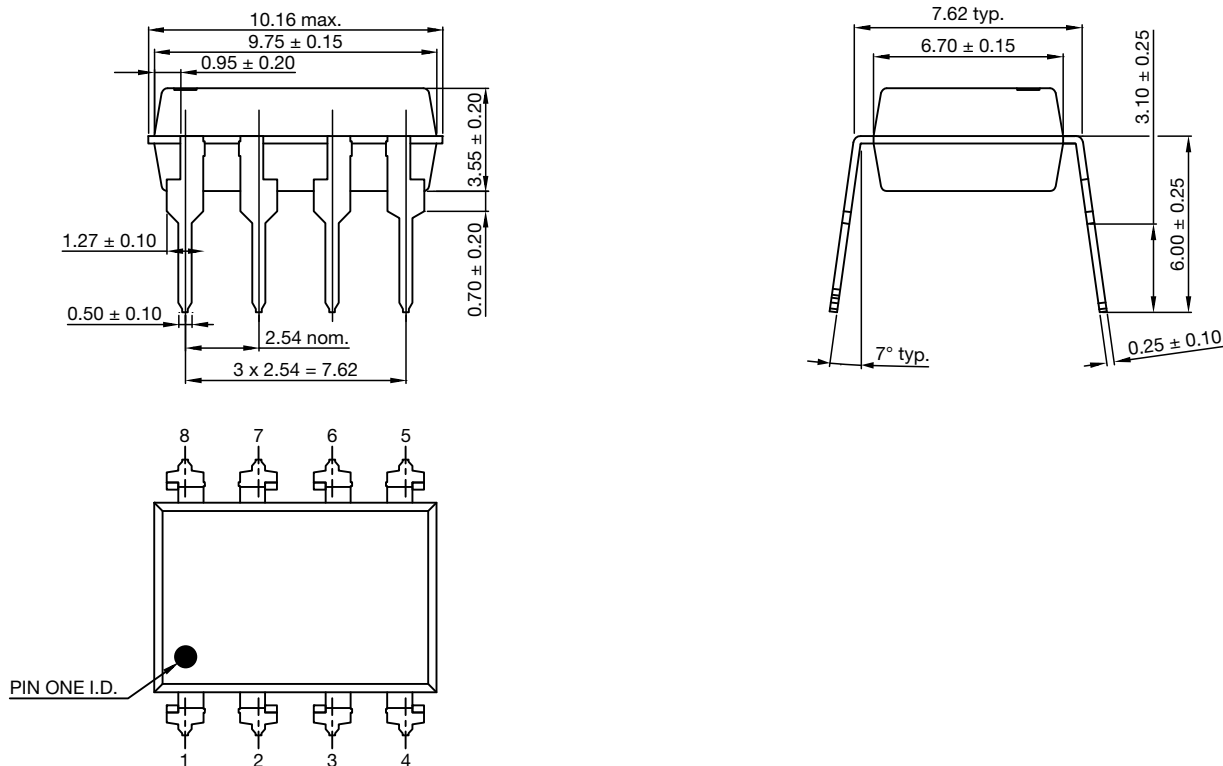


Fig. 11 - Common-Mode Interference Immunity

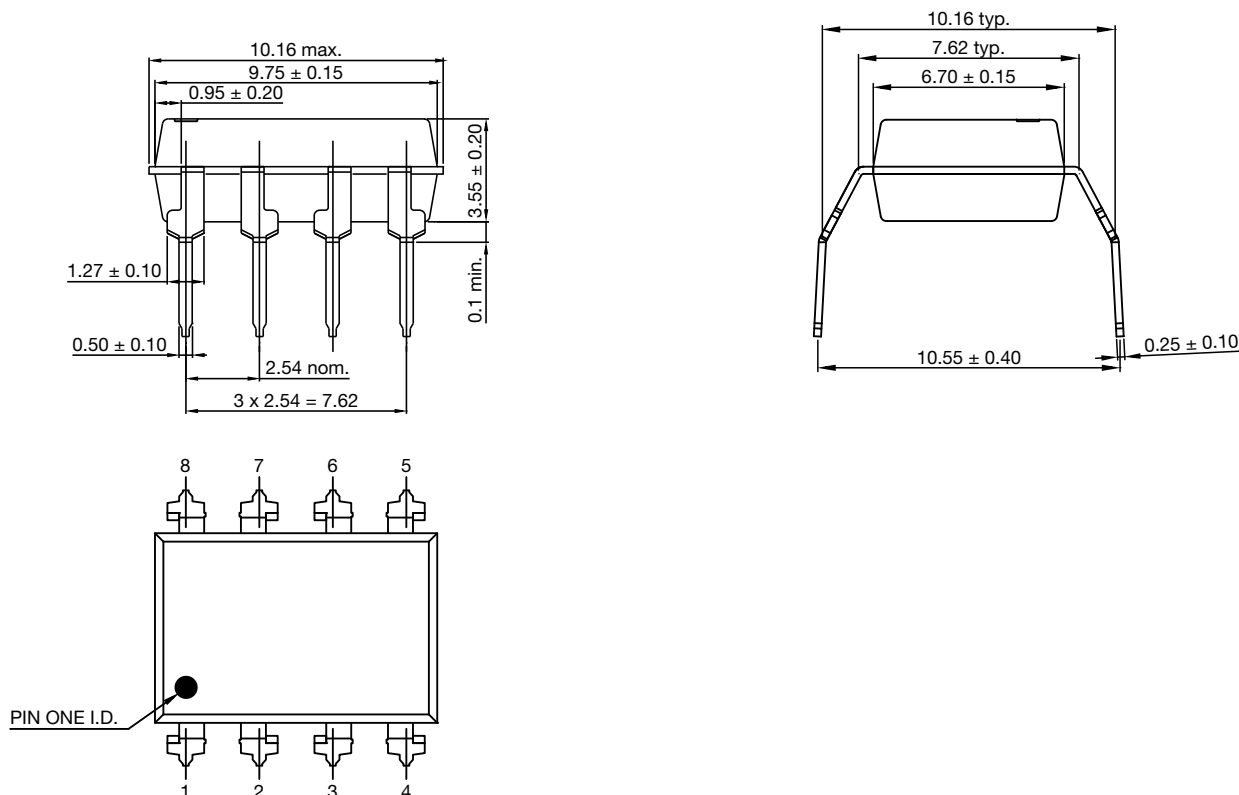


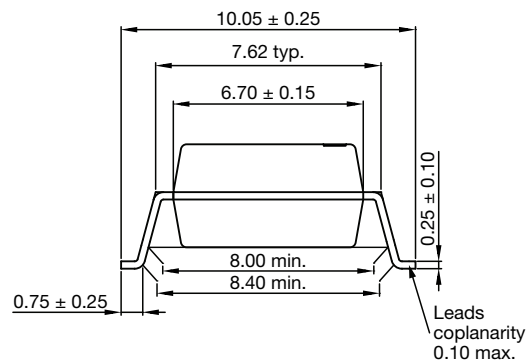
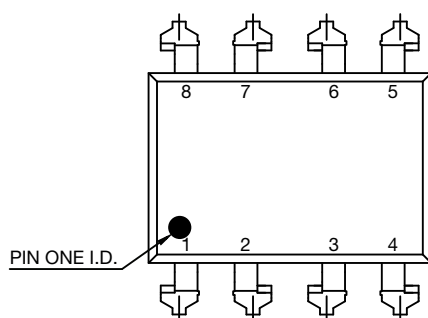
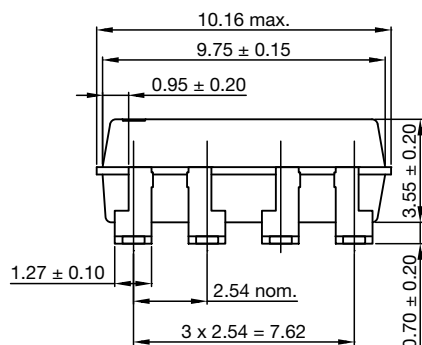
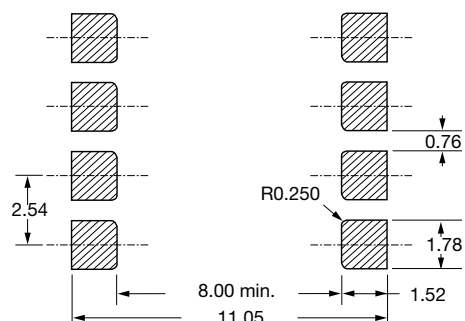
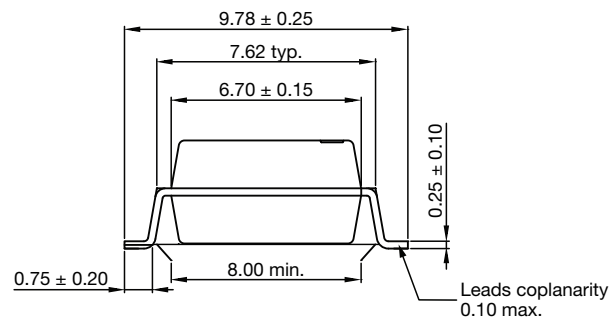
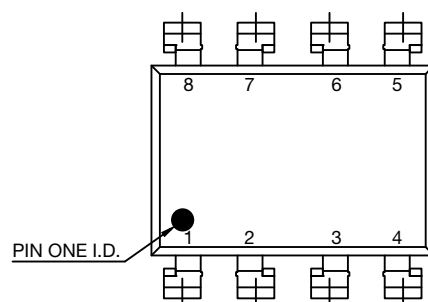
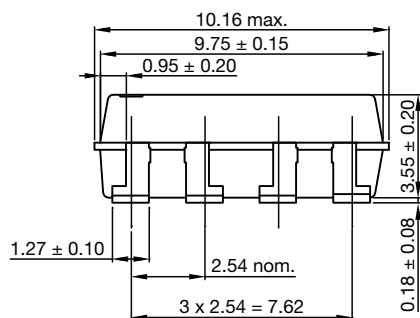
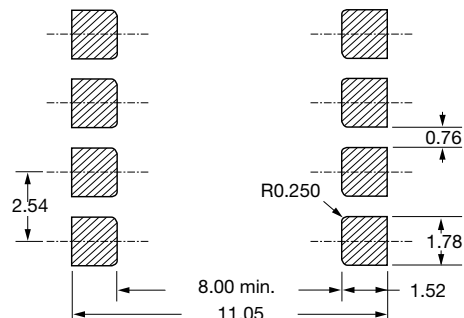
PACKAGE DIMENSIONS (in millimeters)

DIP-8, Standard



DIP-8, Option 6



DIP-8, Option 7

Recommended Footprint

DIP-8, Option 9

Recommended Footprint


PACKAGE MARKING

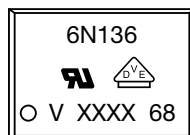


Fig. 12 - 6N136

Notes

- XXXX = LMC (lot marking code)
- The VDE logo is only marked on option 1 parts
- Tape and reel suffix (T) is not part of the package marking

SOLDER PROFILES

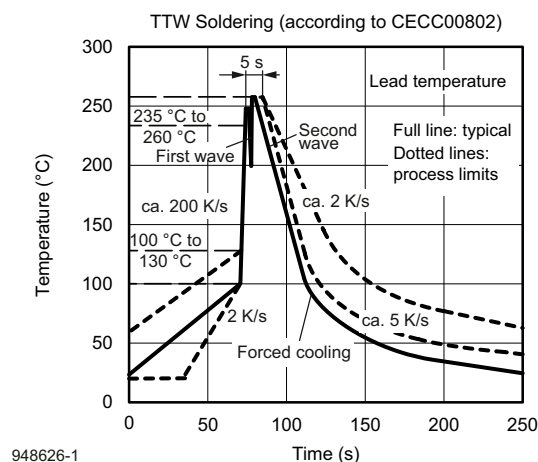


Fig. 13 - Wave Soldering Double Wave Profile According to J-STD-020 for DIP-8 Devices

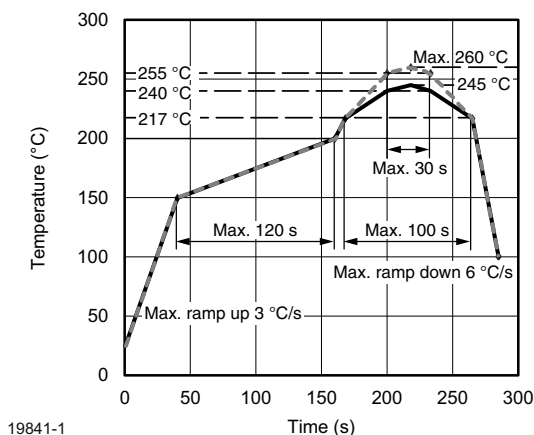


Fig. 14 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020 for SMD-8 Devices

HANDLING AND STORAGE CONDITIONS

ESD level: HBM class 2

Floor life: unlimited

Conditions: $T_{amb} < 30^{\circ}\text{C}$, RH < 85 %

Moisture sensitivity level 1, according to J-STD-020



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